

N° 2018-033-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Capacity expansion by implementation of 300mm wafer diameter for CoolMOS™ products with package TO263

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **28. June 2018**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Eckart Süner
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Product / Process Change Notification



N° 2018-033-A

► Products affected:

Please refer to 1_cip_18033A

► Detailed Change Information:

Subject:

- Expansion of wafer production capacity.
- Implementation of 300mm wafer diameter.

Reason: Capacity Expansion for 300mm wafer production

Description:	Old	New
■ Wafer production site with wafer diameter:	Infineon Technologies (Kulim) Sdn. Bhd., Malaysia (200mm)	Infineon Technologies (Kulim) Sdn. Bhd., Malaysia (200mm)
	Infineon Technologies Austria AG, Villach, Austria (200mm)	Infineon Technologies Dresden GmbH, Germany (300mm)

► Product Identification:

Internal traceability: assured via baunumber, lotnumber and date code

2. External traceability:

a) Lotnumber printed on Barcode Product Label:

PFxxxxxx = 200mm production

ZFxxxxxx = 300mm production

b) Country of diffusion on Barcode Product Label

Malaysia

Germany

► Impact of Change:

Product Quality and Reliability remains the same as proven by product and wafer technology qualification. Product data sheets with all electrical characteristics remain unchanged.

Processes are optimized to meet identical product performance according to the existing Infineon specifications.

► Attachments:

1_cip_18033A	List of affected products
2_cip_18033A	Final qualification report

Product / Process Change Notification



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► Time Schedule:

- | | |
|-------------------------------|---|
| ■ Final qualification report: | available |
| ■ First samples available: | on request |
| ■ Intended start of delivery: | August 2018 or earlier depending on customer approval |

If you have any questions, please do not hesitate to contact your local Sales office.

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Capacity expansion by implementation of 300mm wafer diameter for CoolMOSTM products with package TO263



Old variant description (200mm only)				NEW variant description (300mm only)			
Sales name	SP number	OPN	Package	Sales name	SP number	OPN	Package
IPB60R099C6	SP000687468	IPB60R099C6ATMA1	PG-TO263-3			NA	
IPB60R099CP	SP000088490	IPB60R099CPATMA1	PG-TO263-3			NA	
IPB60R125CP	SP000297368	IPB60R125CPATMA1	PG-TO263-3			NA	
SPB17N80C3	SP000013370	SPB17N80C3ATMA1	PG-TO263-3			NA	
SPB20N60C3	SP000013520	SPB20N60C3ATMA1	PG-TO263-3			NA	
IPB65R045C7	SP000929420	IPB65R045C7ATMA1	PG-TO263-3	IPB65R045C7	SP002447548	IPB65R045C7ATMA2	PG-TO263-3
IPB65R065C7	SP001080110	IPB65R065C7ATMA1	PG-TO263-3	IPB65R065C7	SP002447554	IPB65R065C7ATMA2	PG-TO263-3
IPB65R095C7	SP001080124	IPB65R095C7ATMA1	PG-TO263-3	IPB65R095C7	SP002447562	IPB65R095C7ATMA2	PG-TO263-3
IPB65R125C7	SP001080134	IPB65R125C7ATMA1	PG-TO263-3	IPB65R125C7	SP002447564	IPB65R125C7ATMA2	PG-TO263-3
IPB65R190C7	SP000929424	IPB65R190C7ATMA1	PG-TO263-3	IPB65R190C7	SP002447550	IPB65R190C7ATMA2	PG-TO263-3
IPB65R225C7	SP000992480	IPB65R225C7ATMA1	PG-TO263-3	IPB65R225C7	SP002447552	IPB65R225C7ATMA2	PG-TO263-3

